

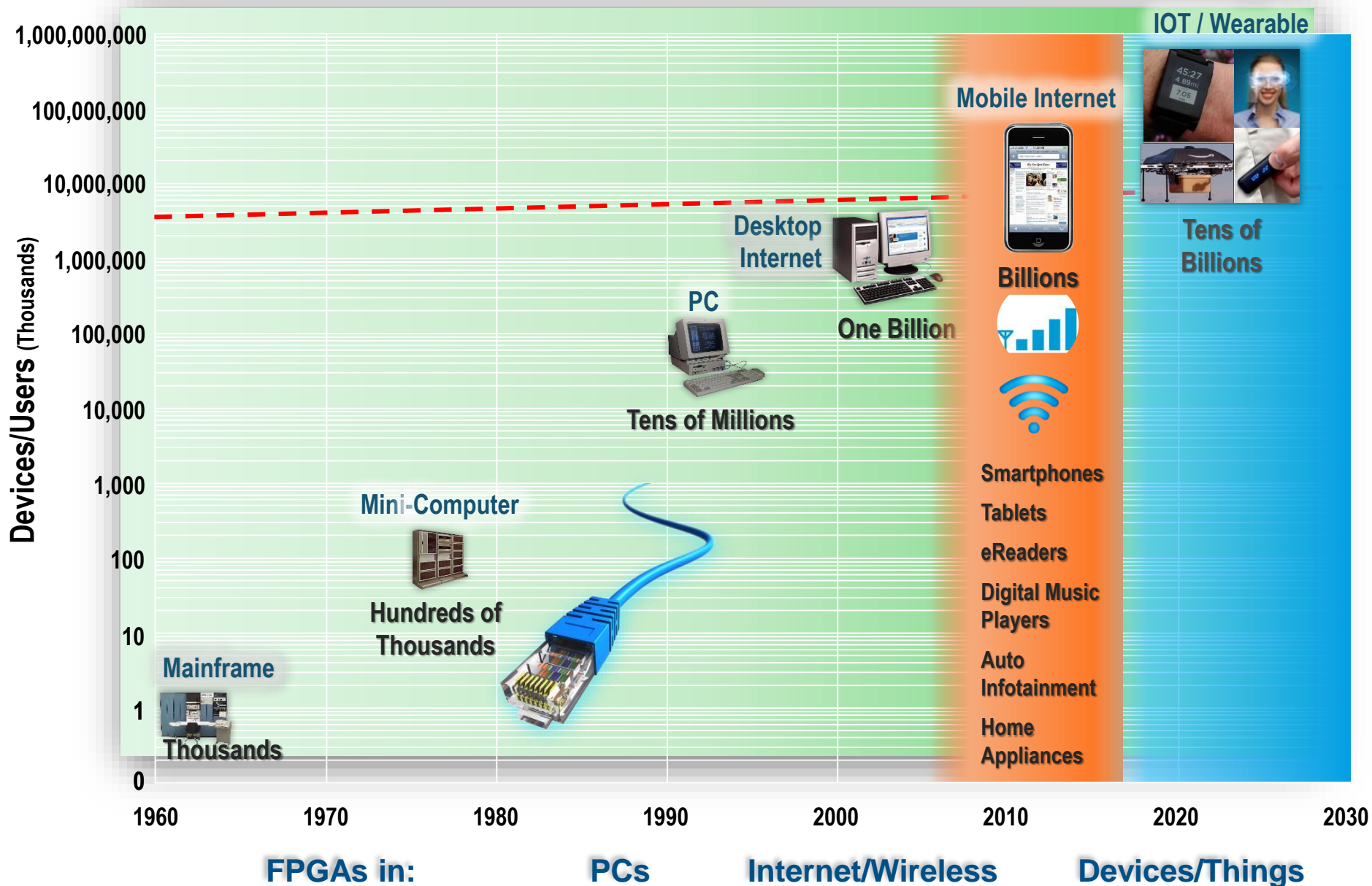
PPP (PRICE, POWER AND PACKAGE)

OPPORTUNITIES FOR INNOVATION IN MOBILE COMPUTING AND IOT

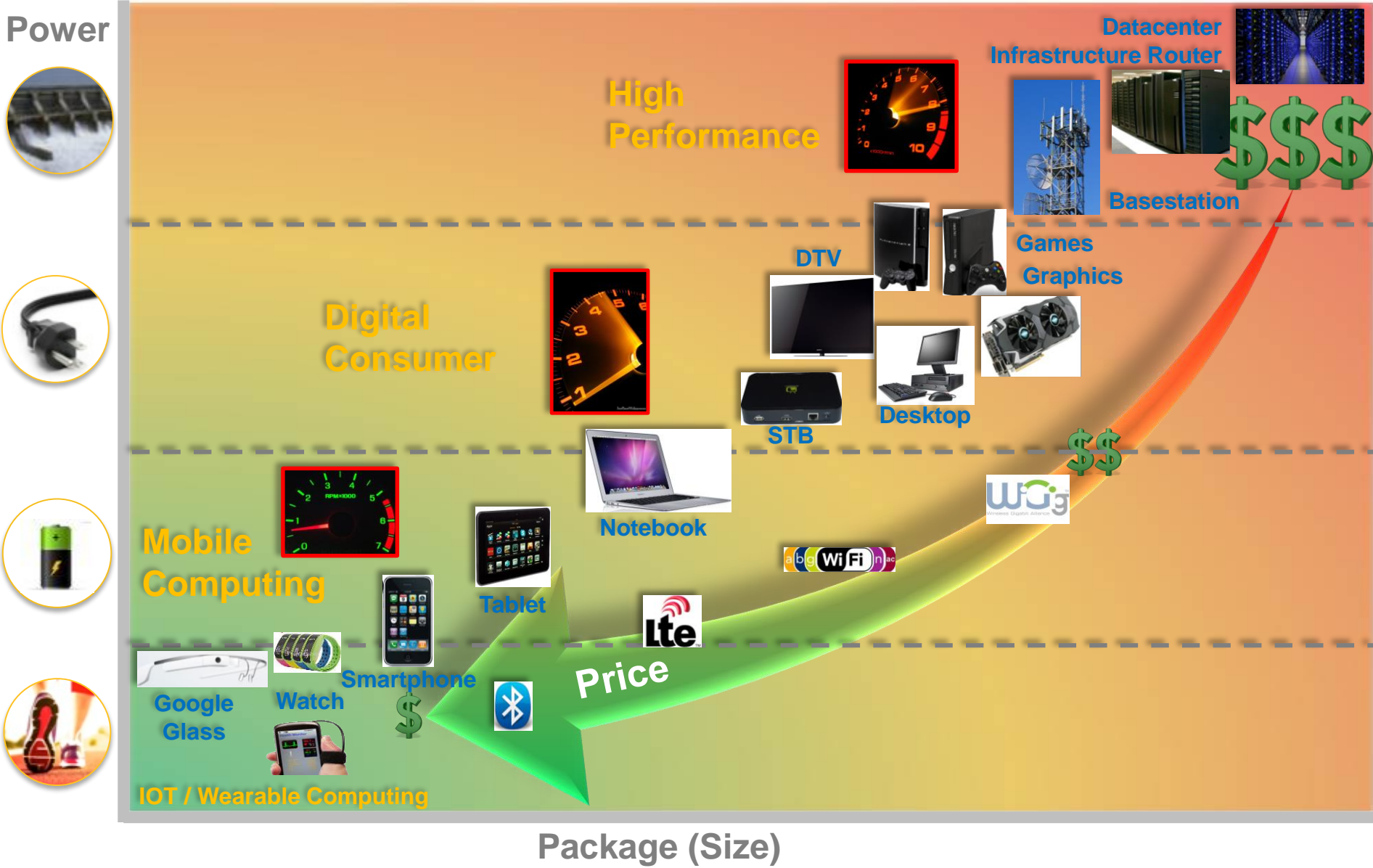
FCCM 2015
May 3, 2015



MOBILE COMPUTING – ENABLING IOT



IOT – REDUCED PRICE, POWER & PACKAGE



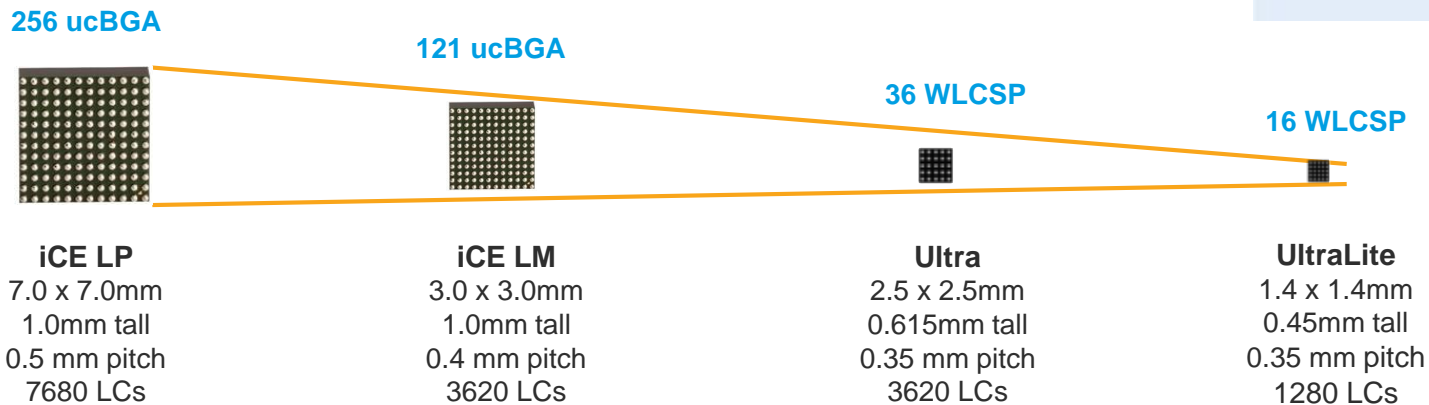
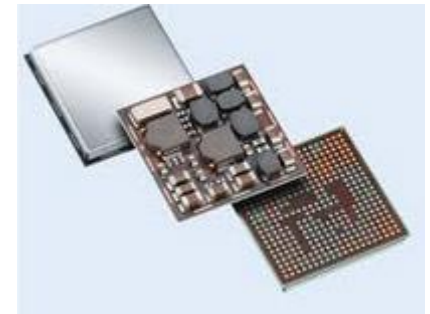
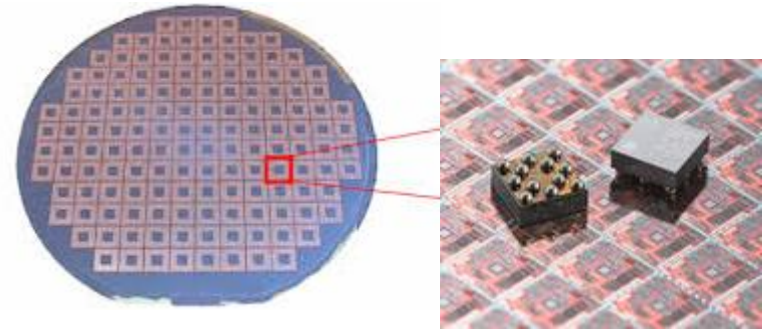
PACKAGING INNOVATIONS FOR MOBILE / IOT



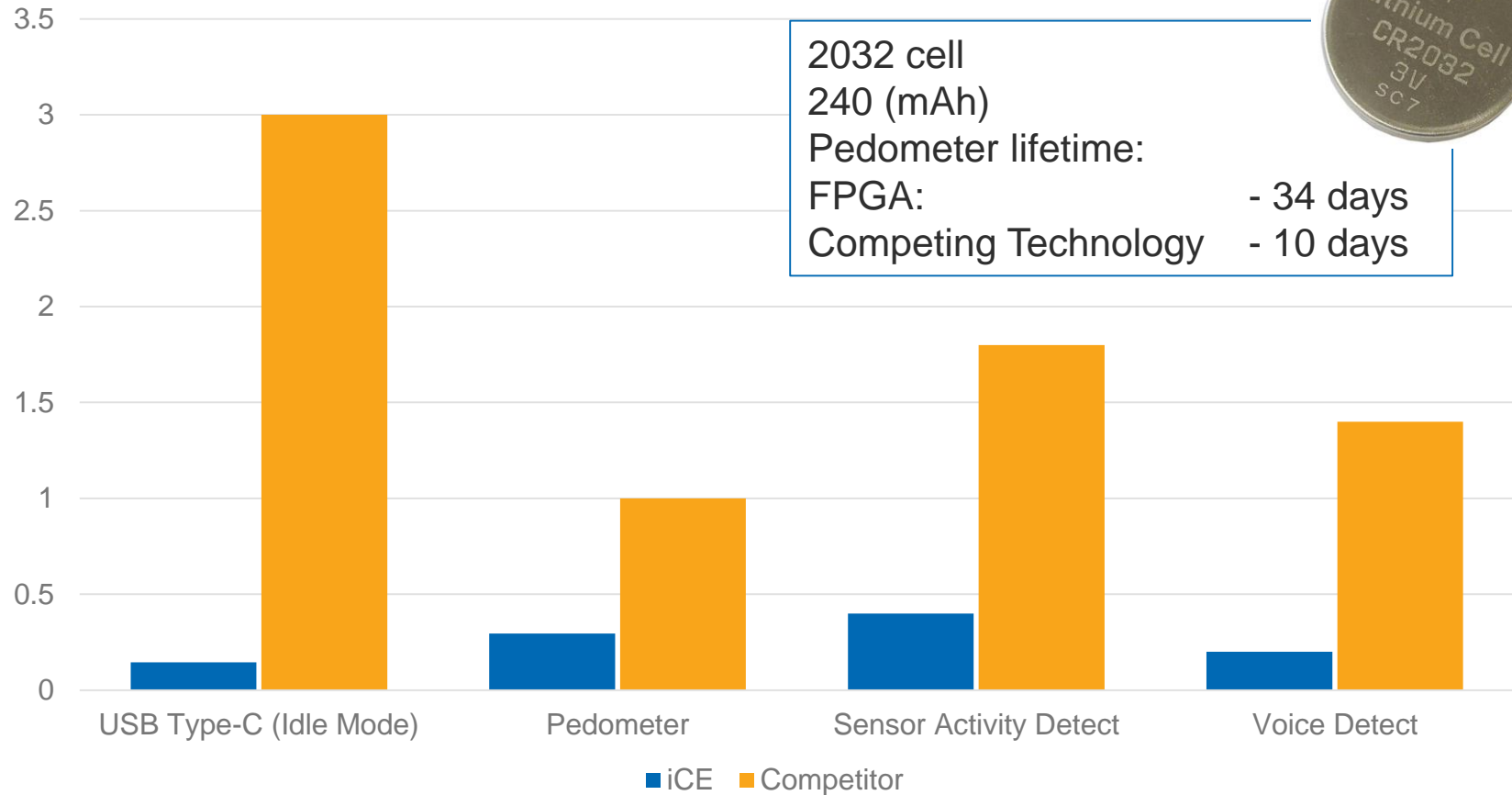
1.4 x 1.4 x 0.45 mm
Ultra

Contributors to Packaging

- Packaging Technology
 - Wire bonding ... migrating to
 - Wafer Level Chip Scale Packaging
- PCB Technology Limits Scaling
- Multi-chip Modules offer opportunities



"Always On" Device Current



Organic Contributors to Power

Device technology

Device geometry

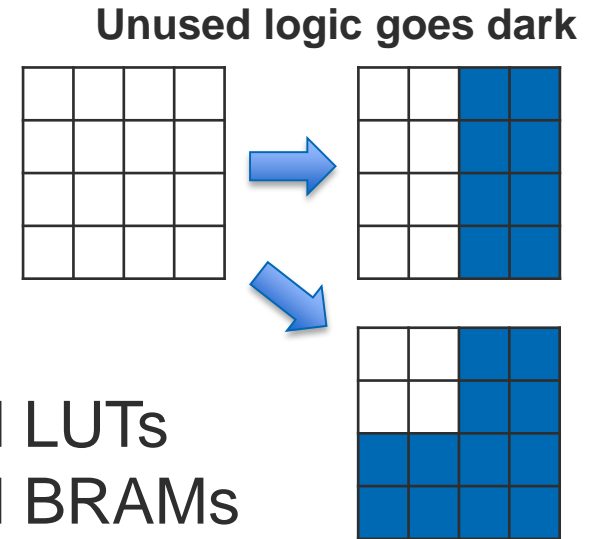
Power optimized design tools

Shut down routing to unused LUTs

Shut down routing to unused BRAMs

Shut down routing to unused Carry Logic

Buffer free interconnects.

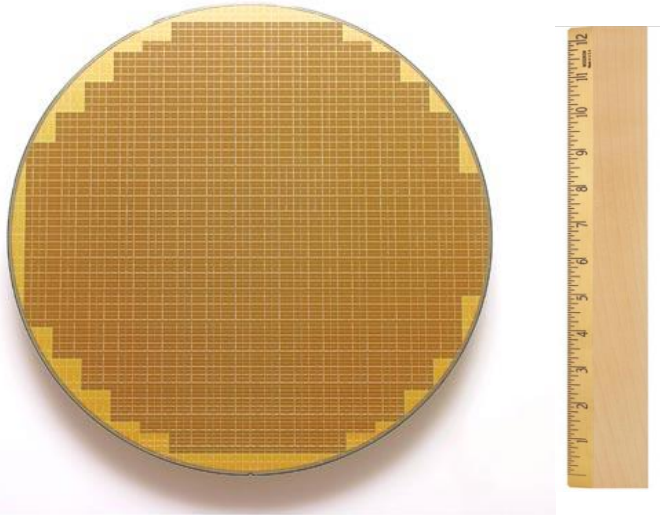


Application Related Contributors to Power

Clock Gating

Parallel State Machines

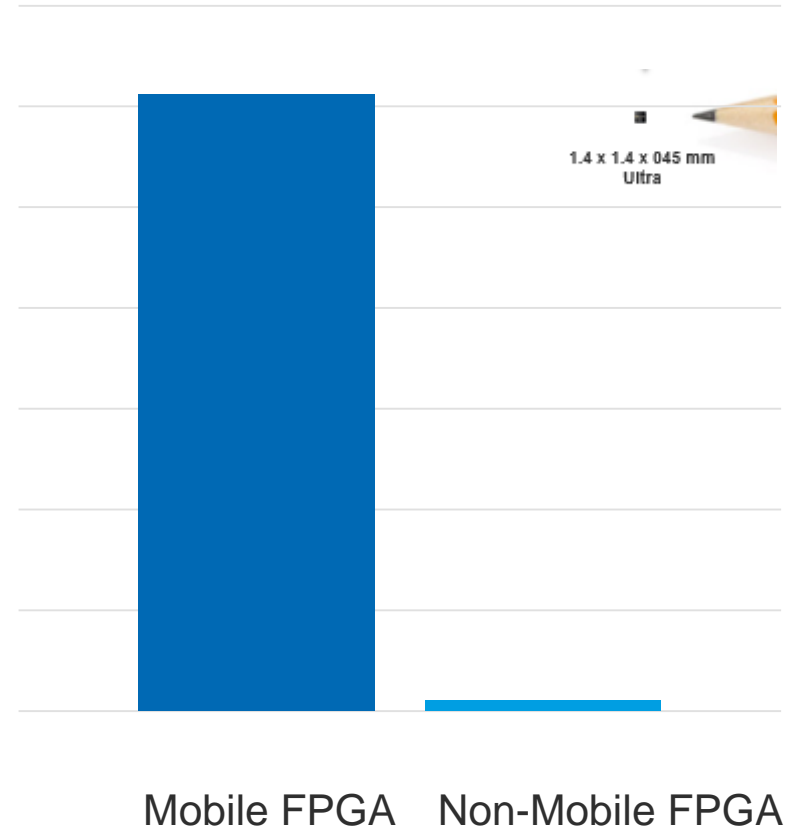
Design Constraints



Contributors to Price

- Economies of Scale
 - 1M per day
- Operational efficiencies
- Device geometry
 - Presently 40nm node
 - Targeting 1 -2 nodes down

DICE PER WAFER



FPGAs IN MOBILE – APPLICABILITY TO IOT

Products	Function	Application
Smartphones / Wearables	Bridge Chips	<ul style="list-style-type: none"> • RFFE bridging for antenna tuning, SDIO, USB Type-C • SLIMbus to I2S, 1 to many I2C
	Timing Critical Offload	<ul style="list-style-type: none"> • IR LED remote control • Indication and LED control
	Sensor Management	<ul style="list-style-type: none"> • Low power “always on” sensor management
	Peripherals	<ul style="list-style-type: none"> • Control logic (Headset control, etc.) • Fingerprint Authentication & Security
Cameras	Video Management	<ul style="list-style-type: none"> • CSI2/DSI to Parallel bridge • Image rotation, Overlay • Custom logic (ASIC companion)
Laptops / Tablets	Panel Interface	<ul style="list-style-type: none"> • TCON, Display Translation
	Sensor management	<ul style="list-style-type: none"> • Low power “always on” sensor management
Smart Batteries/ Ink Cartridges	Authentication	<ul style="list-style-type: none"> • Security and authentication • MIPI BIF / Custom interface

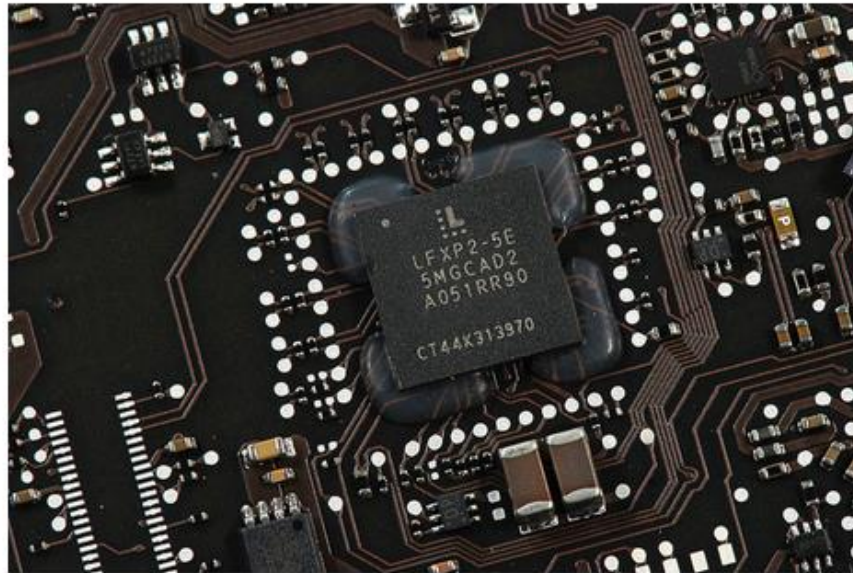


FPGAs IN MOBILE – TEARDOWNS



Apple MacBook Pro Quad-core i7 teardown

By Bill Detwiler , April 5, 2011, 8:03 AM



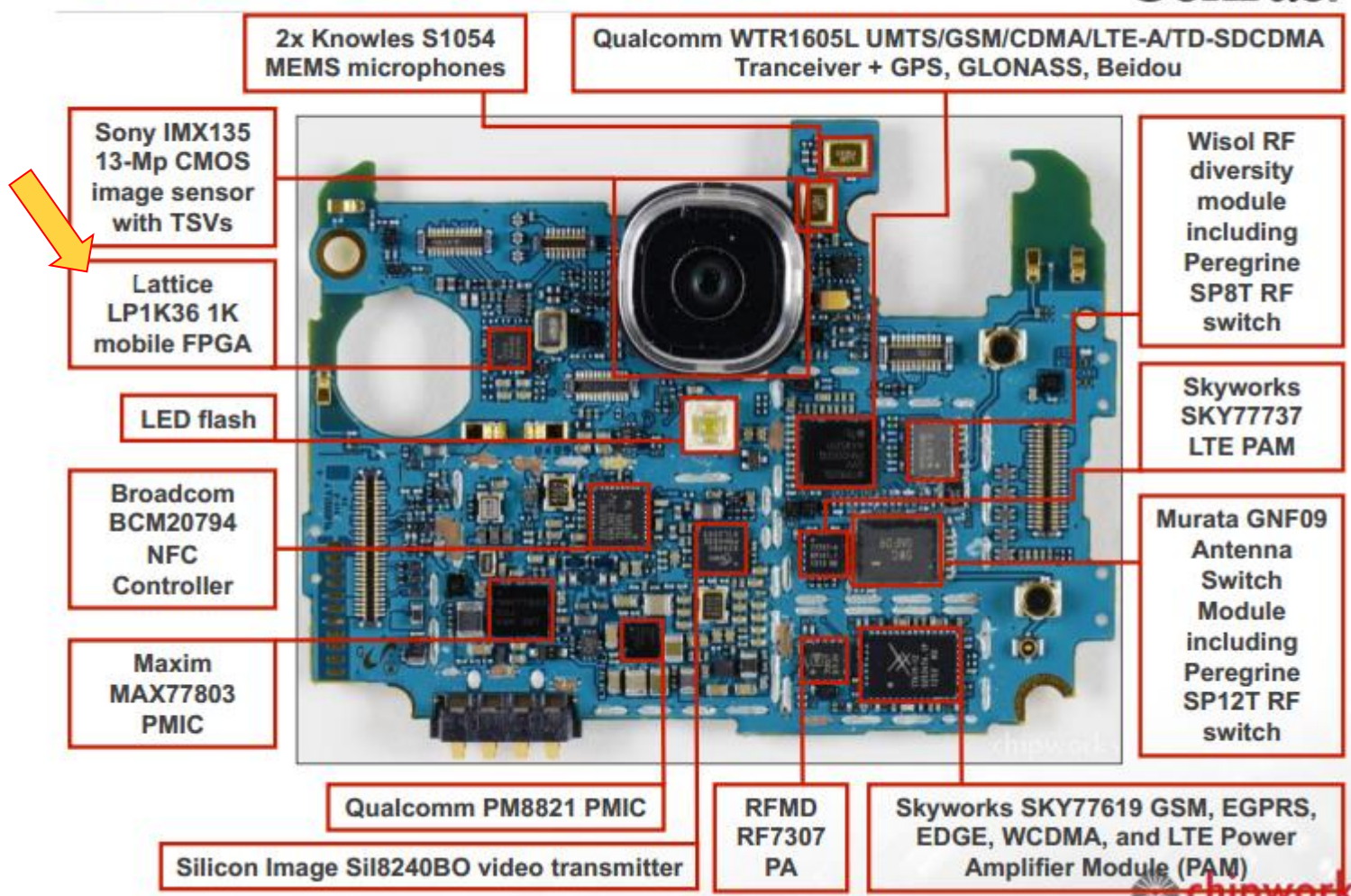
Apple MacBook Pro (2011 Quad-Core i7): Lattice Semiconductor LFXP2-5E

Photo by: Bill Detwiler / TechRepublic
Caption by: Bill Detwiler



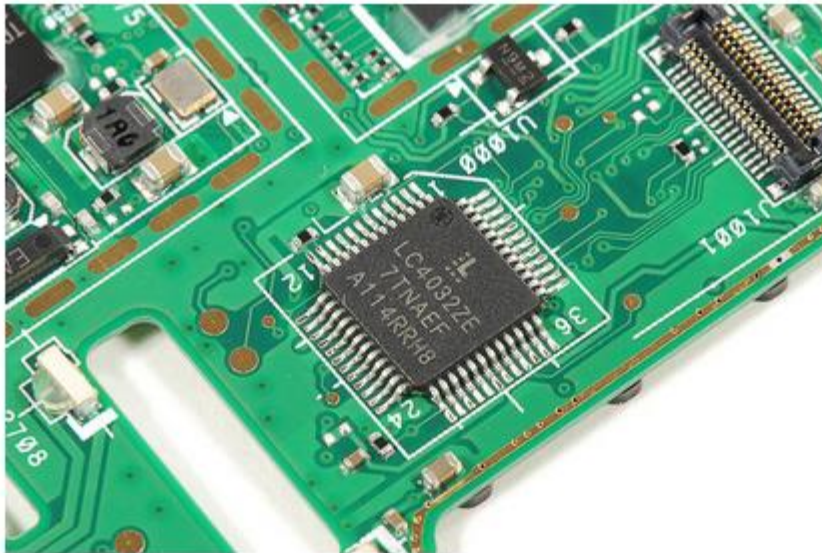
FPGAs IN MOBILE – CHIPWORKS

Samsung Galaxy 4S – Side 2



Cracking Open the 2011 Barnes & Noble Nook e-book reader (Wi-Fi)

By Bill Detwiler , June 8, 2011, 8:22 AM



Cracking Open the 2011 Nook: Lattice Semiconductor ispMACH 4032ZE CPLD

Photo by: Bill Detwiler / TechRepublic
Caption by: Bill Detwiler



FPGAs IN MOBILE – INDICATORS FOR IOT



**Windows
Phone**



ANDROID




3D



Cameras



**eReaders
PNDs
USB Modem
Laptop**

<i>FPGA Perception</i>	<i>FPGA Reality</i>	<i>Notes</i>
Big <u>P</u> ackages	Extremely Small	<ul style="list-style-type: none"> FPGAs are as small as 1.4 mm²
High <u>P</u> ower	Very Low Power	<ul style="list-style-type: none"> Standby Power as low as 21 μW
High <u>P</u> rice	Up to 30K Die Per Wafer	<ul style="list-style-type: none"> FPGAs that are priced as low as \$0.50 in high volume
	High Volume	<ul style="list-style-type: none"> Shipped over 1M units / day

FPGA PRICE, POWER, PACKAGE

Enable Deployment in Mobile and IOT



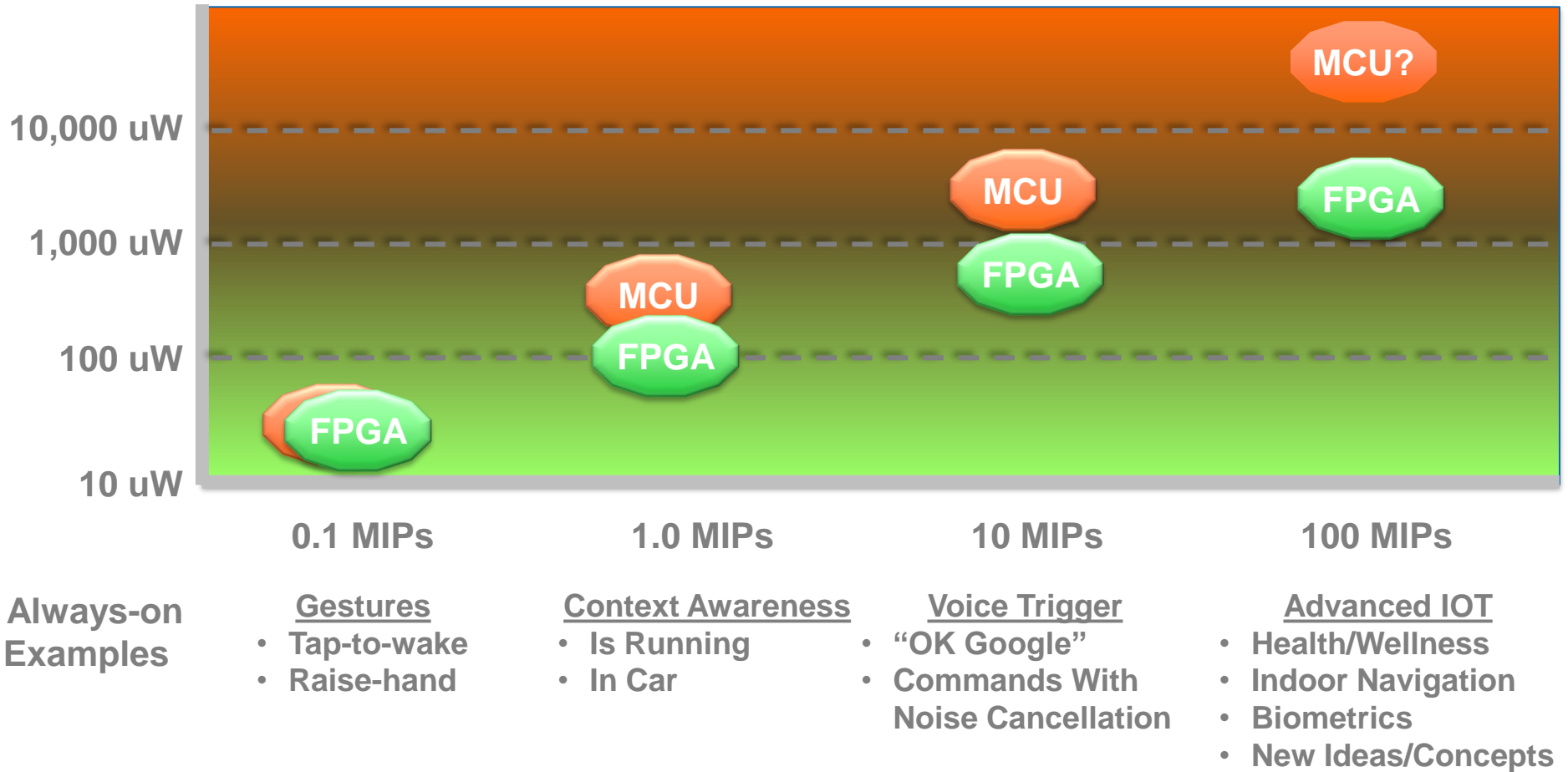
Building a
working
demo
enabled
research on
**critical
pain-points**

Form-factor
compliant IOT
deployment
will uncover
**newer pain-
points and
research fields**

THANK YOU!



FPGA STRENGTH – PARALLELISM



**Reducing FPGA usage barriers for non-RTL algorithm researchers
Within the Mobile and IOT Price/Power/Package**